Materials Declaration Form

IPC **Form Type ***	**1752** Distribute	**Version**	**2**
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ** : Required Field*

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2022-08-16**
Company Unique ID	**NL 008751171B01**		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	**giovanni giacopello**	**Representative Title**	**ADG Material Declaration champion**
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified
Digitally signed by giovanni giacopello
Date: 2022.08.16 16:24:02 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STPST8H100SFY	TA7R*05VED50	A	996I	2022-08-16
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	89.2	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information			
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**	
1	260	3	
Bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00736848

Package Designator	**Package Size**	**Nbr of instances**	**Shape**	
CHP	6.10x4.40x1.10	3	No lead	
Comment	PSMC-3L-EP			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
Exemption Id.	**Description**
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**true**
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.053	die	594
Lead	1.397	soft solder	15661

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				**true**
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
X	O	O	O	O
Soft solder				
Homogeneous Material(s) containing Lead				

QueryList : REACH-17 Jan 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**false**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	1.40	Soft solder	15661
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				**false**
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	1.4	Soft solder	919684

QueryList : Responsible metals sourcing	
Query	**Response**
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	**true**
The following metals are present is the component :	**Gold, Tin, Tungsten,**
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	**Response**
The Product does contain at least one of the substances listed in Chemical Control Act	**false**

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	**Response**
The product contains adhesives identified under GB 33372	**false**

Stockholm Convention Persistent Organic Pollutants	
Query	**Response**
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	**true**

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**TA7R*05VED50**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	2.146	mg	supplier	die	Silicon(Si)	7440-21-3		1.997	mg	930568	22389
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.017	mg	7922	191
				supplier	metallisation	Gold(Au)	7440-57-5		0.018	mg	8388	202
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.053	mg	24697	594
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.007	mg	3262	78
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	466	11
				supplier	polymer coating	Durimide	proprietary		0.053	mg	24697	594
Leadframe & clip	M-004 Copper and its alloys	46.132	mg	supplier	alloy	Copper (Cu)	7440-50-8		44.772	mg	970519	501928
				supplier	alloy	Iron(Fe)	7439-89-6		1.199	mg	25991	13442
				supplier	alloy	Phosphorus(P)	7723-14-0		0.069	mg	1496	774
				supplier	alloy	Zinc(Zn)	7440-66-6		0.092	mg	1994	1031
Soft solder	Solder	1.519	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	1.397	mg	919684	15661
				supplier	solder	Tin(Sn)	7440-31-5		0.076	mg	50033	852
				supplier	solder	Silver(Ag)	7440-22-4		0.038	mg	25016	426
				supplier	solder	dry flux residue	proprietary		0.008	mg	5267	90
Encapsulation	M-011 Other inorganic materials	37.752	mg	supplier	mold compound	Amorphous silica	60676-86-0		32.090	mg	850020	359753
				supplier	mold compound	Epoxy Resin -1	223769-10-6		1.888	mg	50011	21166
				supplier	mold compound	Epoxy Resin-2	85954-11-6		2.265	mg	59997	25392
				supplier	mold compound	Hardener	205830-20-2		1.321	mg	34992	14809
				supplier	mold compound	Carbon Black	1333-86-4		0.188	mg	4980	2108
Connections coating	Solder	1.651	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.651	mg	1000000	18509